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EFM8121

300mm Wafer EFEM

SEMI S2-0715

APPROVED

Characters & Advantages

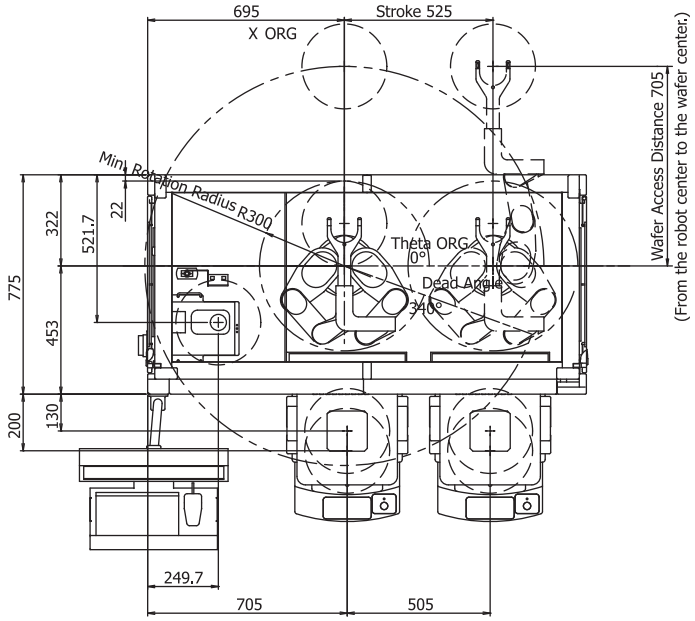
- The equipment can be connected to OHT and AGV.
- The wafer transfer process,customers can choose vacuum or edge-clamp type,depending on their needs.
- The internal mini-environment cleanliness control is verified by the CFD analysis, which ensures the internal and external pressure-differential design to prevent from pollution in the wafer transfer process.
- The compact design can reduce footprint and saves costs.
- Optimized moving track of the robot, enabling a speedy and stable transfer with the curve interpolation for the shortest route.
- The ultra-high speed wafer aligner, which uses the dynamic image algorithm, can accurately and quickly allocate the wafer center and direction.
- With the optical and image processing & identification system,it enhance the identification rate of wafer ID.
- Complete data track to satisfy the requirement of predictive maintenance of Industry 4.0.
- Customized services, providing discussions for customized specifications.

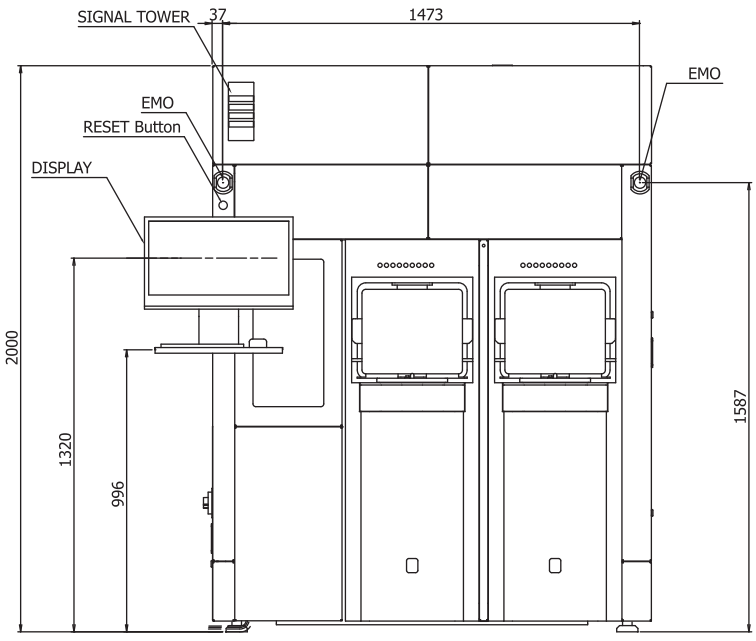
Specification

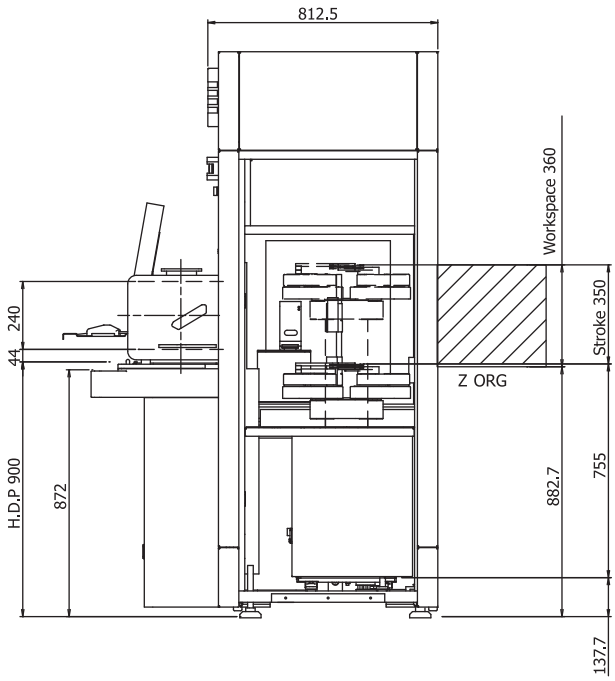
Item	Specification
Number Of Ports	2 Ports
Transferring Object	300mm Wafer : dia.300±0.2mm, Thickness : 775μm
Load Port	TDK TAS300
Robot *	SAD201-R03000705S-Z350
Repeat Accuracy	±0.1mm
Cleanliness	Class 1 @ 0.1μm (PTFE)
Option	Aligner*, Wafer ID Reader, Robot Auto Teaching Function
Power Supply	220VAC 50Hz/60Hz 1PH 6.8KVA
Weight	700 kg

* Vacuum or Edge-Clamp wafer handling is available.

Dimensions







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